

09649160

ABSTRACT OF THE DISCLOSURE

A plurality of lead frames is supplied in lead frame by lead frame sequence. A curable adhesive, preferably a 505 Epoxy, is applied to one surface of each lead frame as it indexes through an application device. An attaching device attaches a device to each lead frame with the adhesive by holding the device in place to cure for a preselected period of time of about one second. Later, the lead frames have their edges trimmed and then are separated into separate lead frames.

5

10

N:\2269\3084.5\cont.pat.app.wpd 8/25/00

09649160.082800